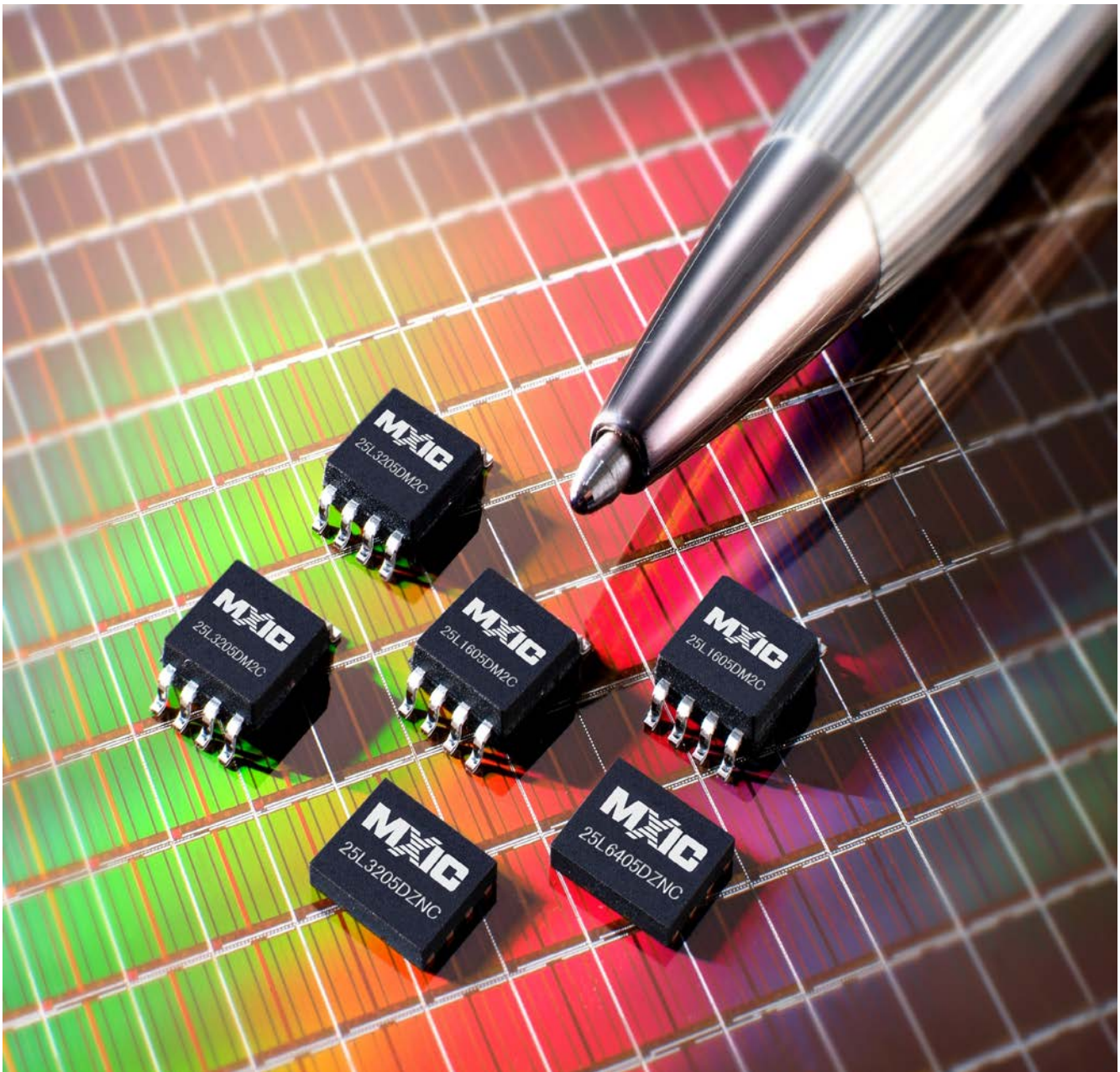




MACRONIX  
INTERNATIONAL Co., LTD.

# Quality & Reliability Quarterly Report

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**1. Quality/Reliability monitoring test items and conditions:**

Test Item	Test Method	Test Conditions	Typical Sample Size (units)
QV (Quality Validation)	JESD86	Per datasheet, at high/room/cold temperatures	All samples
ELFR (Early Life Failure Rate)	JESD22-A108 and JESD74	125 °C, Vcc(max), 48 hrs	2000
NVCE (Non-Volatile Memory Cycling Endurance)	JESD47 JESD22-A117 AEC-Q100-005D (For Automotive Product)	Half samples at 25 °C, half samples at max operating Temperature, 1K/10K/100K Program/Erase cycles. For flash products only.	77 Automotive Product: Sum of sample size for HTDR, LTDR, and HTOL
LTDR (NVM Low Temperature Retention and Read Disturb)	JESD47 JESD22-A117 AEC-Q100-005D (For Automotive Product)	25 °C, Vcc(max), 168hrs/500hrs. For flash products only.	38
HTDR (High Temperature Data Retention)	JESD47 JESD22-A117 AEC-Q100-005D (For Automotive Product)	125 °C, 10hrs/100hrs or equivalent stress time per lifetime model. For flash products only.	39
HTOL (High Temperature Operating Life)	JESD22-A108 JESD85 AEC-Q100-005D (For Automotive Product)	125 °C, Vcc(max), 168hrs/500hrs/1000hrs (For Automotive Product with P/E cycle pre-conditioning)	77 Automotive Product:77
HTSL (High Temperature Storage Life)	JESD22-A103	150 °C, 168hrs/500hrs/1000hrs	77
PC (Pre-conditioning)	JESD22-A113	TCT(-65 °C to 150 °C) 10 cycles, IR reflow 3 cycles, HTSL 125 °C 24hrs, 30 °C/60%RH 192hrs (MSL 3)	All SMD samples before TCT, PCT, HAST
TCT (Temperature Cycle Test)	JESD22-A104	-65°C ↔ 150°C (condition C), 200/500 cycles	77
PCT (Pressure Cooker Test)	JESD22-A102	121 °C, 100%RH, 2 atm, 96hrs	77
HAST (Highly Accelerated Temperature and Humidity Stress Test)	JESD22-A110	130°C, 85% RH, 33.3 psia, Vcc(max), 96hrs	77
ESD (Electro-Static Discharge)	JS-001-2012 (HBM) JS-002-2014 (CDM)	NTD: 1000V or till failure HBM: 500~2000V or till failure CDM : 750 or till failure Optional test in response to specific customer	3



**2. Flash Quarterly reliability monitor results:**

2-1. Quality Validation & Early Life Failure Rate :

Tech.	EPN Code	QV		ELFR	
		SS	Reject	SS	Reject
0.15 μm	MX29F400C	2000	0	2000	0
0.13 μm	MX29LV160D	2000	0	2000	0
0.11 μm	MX25L12845E	2000	0	2000	0
	MX25L3206E	2000	0	*1	*1
	MX25U1635E	*1	*1	*1	*1
	MX29GL256E	600	0	*2	*2
	MX25L3206E	600	0	*2	*2
75 nm	MX25L12835F	2000	0	2000	0
	MX25L12835F	2000	0	*1	*1
	MX25R8035F	2000	0	*1	*1
	MX25R8035F	2000	0	*1	*1
	MX30LF1G08AA	*1	*1	*1	*1
	MX29GL128F	600	0	*2	*2
55 nm	MX25L25645G	2000	0	2000	0
	MX25L25645G	600	0	*2	*2
	MX25U51245G	600	0	*2	*2
36 nm	MX30LF1G18AC	*1	*1	*1	*1
	MX30LF4G18AC	600	0	*2	*2

\*1: Means the test is “on going”. The results will be updated next quarter.

\*2 : No ELFR test, the samples are only used for QV and NVCE test.

2-2. Non-Volatile Memory Cycling Endurance Test :

Tech.	EPN Code	NVCE@25°C		NVCE@85°C	
		SS	Reject	SS	Reject
0.15 μm	MX29F400C	154	0	77	0
0.13 μm	MX29LV160D	38	0	39	0
0.11 μm	MX25L12845E	38	0	39	0
	MX25L3206E	38	0	39	0
	MX25U1635E	*1	*1	*1	*1
75 nm	MX25L12835F	38	0	39	0
	MX25L12835F	38	0	39	0
	MX25R8035F	38	0	39	0
	MX25R8035F	38	0	39	0
	MX30LF1G08AA	*1	*1	*1	*1
55 nm	MX25L25645G	38	0	39	0
36 nm	MX30LF1G18AC	*1	*1	*1	*1

\*1: Means the test is “on going”. The results will be updated next quarter.





2-3. Data Retention Test :

Tech.	EPN Code	LTDR@25°C 500hrs		HTDR@125°C 100hrs	
		SS	Reject	SS	Reject
0.13 μm	MX29LV160D	38	0	39	0
0.11 μm	MX25L12845E	38	0	39	0
	MX25L3206E	*1	*1	*1	*1
	MX25U1635E	*1	*1	*1	*1
75 nm	MX25L12835F	38	0	39	0
	MX25L12835F	*1	*1	39	0
	MX25R8035F	*1	*1	*1	*1
	MX25R8035F	*1	*1	*1	*1
	MX30LF1G08AA	*1	*1	*1	*1
55 nm	MX25L25645G	*1	*1	39	0
36 nm	MX30LF1G18AC	*1	*1	*1	*1

\*1: Means the test is “on going”. The results will be updated next quarter.

2-4. Non-Volatile Memory Program/ Erase Endurance, Data Retention and Operation Life Test (For Automotive Product)

a. High Temperature

Tech.	EPN Code	NVCE@105°C		HTDR@150°C 500hrs		HTOL@125°C 1000hrs	
		SS	Reject	SS	Reject	SS	Reject
0.11 μm	MX29GL256E	116	0	39	0	77	0
	MX25L3206E	116	0	*1	*1	*1	*1
75 nm	MX29GL128F	116	0	39	0	77	0
55 nm	MX25L25645G	116	0	*1	*1	*1	*1
	MX25U51245G	116	0	*1	*1	*1	*1

\*1: Means the test is “on going”. The results will be updated next quarter.

Tech.	EPN Code	NVCE@105°C		HTDR@150°C 92hrs		HTOL@125°C 1000hrs	
		SS	Reject	SS	Reject	SS	Reject
36 nm	MX30LF4G18AC	116	0	39	0	*1	*1

\*1: Means the test is “on going”. The results will be updated next quarter.



b. Low Temperature

Tech.	EPN Code	NVCE@25°C		LTDR@25°C 1000hrs	
		SS	Reject	SS	Reject
0.11 μm	MX29GL256E	38	0	38	0
	MX25L3206E	38	0	*1	*1
75 nm	MX29GL128F	38	0	38	0
55 nm	MX25L25645G	38	0	*1	*1
	MX25U51245G	*1	*1	*1	*1
36 nm	MX30LF4G18AC	38	0	*1	*1

\*1: Means the test is “on going”. The results will be updated next quarter.

2-5. High Temperature Operating Life and High Temperature Storage Life Test:

Tech.	EPN Code	HTOL 1000hrs		HTSL 1000hrs	
		SS	Reject	SS	Reject
0.15 μm	MX29F400C	*1	*1	*1	*1
0.13 μm	MX29LV160D	77	0	77	0
0.11 μm	MX25L12845E	77	0	77	0
	MX25L3206E	*1	*1	*1	*1
	MX25U1635E	*1	*1	*1	*1
75 nm	MX25L12835F	77	0	77	0
	MX25L12835F	*1	*1	*1	*1
	MX25R8035F	*1	*1	*1	*1
	MX25R8035F	77	0	77	0
	MX30LF1G08AA	*1	*1	*1	*1
55 nm	MX25L25645G	77	0	77	0
36 nm	MX30LF1G18AC	*1	*1	*1	*1

\*1: Means the test is “on going”. The results will be updated next quarter.



2-6. Pre-Condition Test / Pressure Cooker Test / Temperature Cycling Test / Highly Accelerated Temperature and Humidity Stress Test:

Tech.	EPN Code	PC		TCT 500cycles		PCT 96hrs		HAST 96hrs	
		SS	Reject	SS	Reject	SS	Reject	SS	Reject
0.15 $\mu$ m	MX29F400C	231	0	77	0	77	0	77	0
0.13 $\mu$ m	MX29LV160D	231	0	77	0	77	0	77	0
0.11 $\mu$ m	MX25L12845E	231	0	77	0	77	0	77	0
	MX25L3206E	231	0	77	0	77	0	77	0
	MX25U1635E	*1	*1	*1	*1	*1	*1	*1	*1
75 nm	MX25L12835F	231	0	77	0	77	0	77	0
	MX25L12835F	231	0	77	0	77	0	77	0
	MX25R8035F	231	0	*1	*1	77	0	77	0
	MX25R8035F	231	0	77	0	77	0	77	0
	MX30LF1G08AA	*1	*1	*1	*1	*1	*1	*1	*1
55 nm	MX25L25645G	231	0	77	0	77	0	77	0
36 nm	MX30LF1G18AC	*1	*1	*1	*1	*1	*1	*1	*1

\*1: Means the test is "on going". The results will be updated next quarter.



**3. XtraROM Quarterly reliability monitor results:**

3-1. Quality Validation & Early Life Failure Rate:

Tech.	Product Code	QV		ELFR	
		SS	Reject	SS	Reject
65 nm	5218N	385	0	385	0
45 nm	5245N	385	0	385	0

3-2. High Temperature Operating Life and High Temperature Storage Life Test:

Tech.	Product Code	HTOL 1000hrs		HTSL 1000hrs	
		SS	Reject	SS	Reject
65 nm	5218N	77	0	77	0
45 nm	5245N	77	0	77	0

3-3. Pre-Condition Test / Pressure Cooker Test / Temperature Cycling Test / Highly Accelerated Temperature and Humidity Stress Test:

Tech.	Product Code	PC		TCT 500cycles		PCT 96hrs		HAST 96hrs	
		SS	Reject	SS	Reject	SS	Reject	SS	Reject
65 nm	5218N	231	0	77	0	77	0	77	0
45 nm	5245N	231	0	77	0	77	0	77	0

3-4. Electrostatic Discharge Sensitivity Test:

Tech.	Product Code	Mode	Classification	SS	Reject
65 nm	5218N	HBM	2.0 KV	3	0
			2.5 KV	3	0
			3.0 KV	3	0
		CDM	0.75 KV	3	0
		NTD	1.0 KV	12	0
45 nm	5245N	HBM	2.0 KV	3	0
			2.5 KV	3	0
		CDM	0.75 KV	6	0
		NTD	1.0 KV	9	0